2-Bit Bus Switch

7WB3306

The 7WB3306 is an advanced high-speed low-power 2-bit bus switch in ultra-small footprints.

Features

- High Speed: $t_{PD} = 0.25 \text{ ns (Max)} @ V_{CC} = 4.5 \text{ V}$
- 3 Ω Switch Connection Between 2 Ports
- Power Down Protection Provided on Inputs
- Zero Bounce
- TTL-Compatible Control Inputs
- Ultra-Small Pb-Free Packages
- These are Pb-Free Devices



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MARKING DIAGRAMS



UDFN8 MU SUFFIX CASE 517AJ



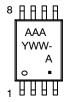


Micro8 DM SUFFIX CASE 846A





TSSOP8 DT SUFFIX CASE 948AL





UDFN8 1.95 x 1.0 CASE 517CA



A = Assembly Location

Y = Year
W = Work Week
M = Date Code
= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

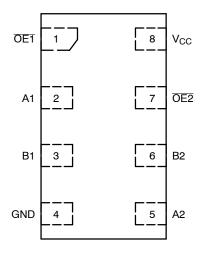


Figure 1. UDFN8 (Top Thru-View)

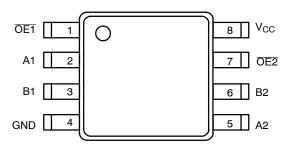


Figure 2. Micro8/TSSOP8 (Top View)

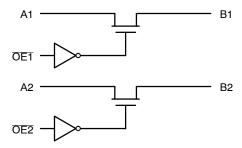


Figure 3. Logic Diagram

FUNCTION TABLE

Input OEn	Function
L	Bn = An
Н	Disconnect

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage	-0.5 to +7.0	V
V _{IN}	Control Pin Input Voltage	-0.5 to +7.0	V
V _{I/O}	Switch Input / Output Voltage	-0.5 to +7.0	V
I _{IK}	Control Pin DC Input Diode Current V _{IN} < GND	-50	mA
I _{OK}	Switch I/O Port DC Diode Current V _{I/O} < GND	-50	mA
I _O	ON-State Switch Current	± 128	mA
	Continuous Current Through V _{CC} or GND	± 150	mA
Icc	DC Supply Current Per Supply Pin	± 150	mA
I _{GND}	DC Ground Current per Ground Pin	± 150	mA
T _{STG}	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
TJ	Junction Temperature Under Bias	150	°C
$\theta_{\sf JA}$	Thermal Resistance UDFN8 (Note 1) Micro8 TSSOP8	111 392 150	°C/W
P_{D}	Power Dissipation in Still Air at 85°C UDFN8 Micro8 TSSOP8	1127 319 833	mW
MSL	Moisture Sensitivity	Level 1	
F _R	Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage (Note 2) Human Body Model, all pins Human Body Model, A_n/B_n to Ground Human Body Model, A_n/B_n to V_{CC}	> 1.5 > 4 > 4	kV kV kV
I _{LATCHUP}	Latchup Performance Above V _{CC} and Below GND at 125°C (Note 3)	±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.
- Tested to EIA / JESD22-A114-A.
 Tested to EIA / JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit	
V _{CC}	Positive DC Supply Voltage	4.0	5.5	V	
V _{IN}	Control Pin Input Voltage	0	5.5	V	
V _{I/O}	Switch Input / Output Voltage	0	5.5	V	
T _A	Operating Free-Air Temperature	-55	+125	°C	
Δt/ΔV	Input Transition Rise or Fall Rate	Control Input Switch I/O	0	5 DC	nS/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

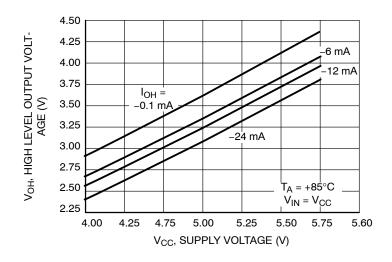
		V _{CC}			T _A = 25°C		T _A = -55°C to +125°C		
Symbol	Parameter	Conditions	(V)	Min	Тур	Max	Min	Max	Unit
V _{IK}	Clamp Diode Voltage	I _{I/O} = -18 mA	4.5			-1.2		-1.2	V
V _{IH}	High-Level Input Voltage (Control)		4.0 to 5.5	2.0			2.0		V
V _{IL}	Low-Level Input Voltage (Control)		4.0 to 5.5			0.8		0.8	V
V _{OH}	Output Voltage High	See Figure 4							
I _{IN}	Input Leakage Current	$0 \le V_{IN} \le 5.5 V$	5.5			± 0.1		±1.0	μΑ
I _{OFF}	Power Off Leakage Current	V _{I/O} = 0 to 5.5 V	0			± 0.1		±1.0	μΑ
I _{CC}	Quiescent Supply Current	I _O = 0, V _{IN} = V _{CC} or 0 V	5.5			± 0.1		±1.0	μΑ
Δl _{CC}	Increase in Supply Current (Control Pin)	One input at 3.4 V; Other inputs at V _{CC} or GND	5.5					2.5	mA
R _{ON}	Switch ON Resistance	V _{I/O} = 0, I _{I/O} = 64 mA I _{I/O} = 30 mA	4.5		3 3	7 7		7 7	Ω
		V _{I/O} = 2.4, I _{I/O} = 15 mA			6	15		15	
		V _{I/O} = 2.4, I _{I/O} = 15 mA	4.0		10	20		20	

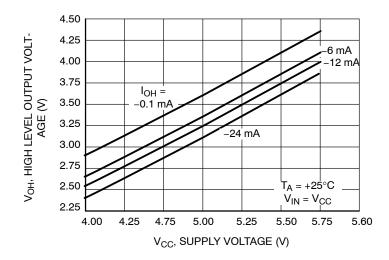
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

AC ELECTRICAL CHARACTERISTICS

			V _{CC}	T _A = 25 °C		T _A = -55°C to +125°C			
Symbol	Parameter	Test Condition	(V)	Min	Тур	Max	Min	Max	Unit
t _{PD}	Propagation Delay, Bus to Bus	See Figure 5	4.0 to 5.5			0.25		0.25	ns
t _{EN}	Output Enable Time	See Figure 5	4.5 to 5.5	0.8	2.5	4.2	0.8	4.2	ns
			4.0	0.8	3.0	4.6	0.8	4.6	
t _{DIS}	Output Disable Time		4.5 to 5.5	0.8	3.0	4.8	0.8	4.8	ns
			4.0	0.8	2.9	4.4	0.8	4.4	
C _{IN}	Control Input Capacitance	V _{IN} = 5 or 0 V	5.0		2.5				pF
C _{IO(ON)}	Switch On Capacitance	Switch ON	5.0		10				pF
C _{IO(OFF)}	Switch Off Capacitance	Switch OFF	5.0		5				pF

TYPICAL DC CHARACTERISTICS





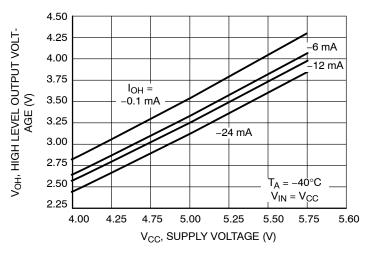
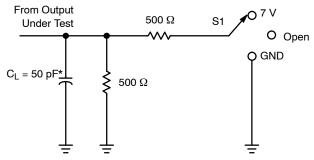


Figure 4. Output Voltage High vs Supply Voltage

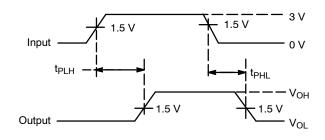
AC LOADING AND WAVEFORMS

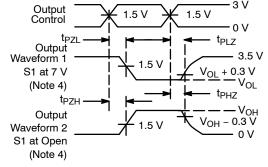
Parameter Measurement Information



Test	S1
t _{PD}	Open
t _{PLZ} /t _{PZL}	7 V
t _{PHZ} /t _{PZH}	Open

^{*}CL includes probes and jig capacitance.





Voltage Waveforms Propagation Delay Times

Voltage Waveforms Enable and Disable Times

- 4. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control
- 5. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_0 = 50 Ω , $t_r \leq$ 2.5 ns, $t_f \leq$ 2.5 ns. 6. The outputs are measured one at a time, with one transition per measurement.
- t_{PLZ} and t_{PHZ} are the same as t_{DIS}.
- 8. t_{PZL} and t_{PZH} are the same as t_{EN}.
 9. t_{PHL} and t_{PLH} are the same as t_{PD}.

Figure 5. t_{PD}, t_{EN}, t_{DIS} Loading and Waveforms

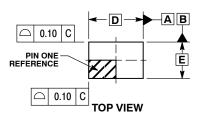
ORDERING INFORMATION

Device	Package	Shipping [†]
7WB3306MUTAG	UDFN8 (Pb-Free)	3000 / Tape & Reel
7WB3306DMR2G	Micro8 (Pb-Free)	4000 / Tape & Reel
7WB3306DTR2G	TSSOP8 (Pb-Free)	5000 / Tape & Reel
7WB3306DMUTCG	UDFN8, 1.95 x 1.0, 0.5 mm Pitch (Pb-Free)	3000 / Tape & Reel

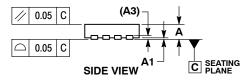
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

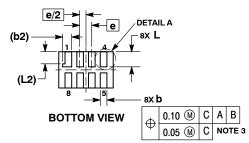
PACKAGE DIMENSIONS

UDFN8 1.8 x 1.2, 0.4P CASE 517AJ ISSUE O





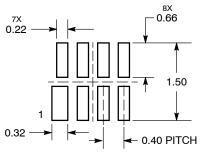




- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.
 4. MOLD FLASH ALLOWED ON TERMINALS ALONG EOGE OF PACKAGE, FLASH MAY NOT EXCEED 0.03 ONTO BOTTOM SURFACE OF TERMINALS.
 5. DETAIL A SHOWS OPTIONAL CONSTRUCTION FOR TERMINALS.

	MILLIMETERS				
DIM	MIN MAX				
Α	0.45	0.55			
A 1	0.00	0.05			
А3	0.127 REF				
b	0.15 0.25				
b2	0.30	REF			
ם	1.80	BSC			
Е	1.20	BSC			
Φ	0.40	BSC			
L	0.45 0.55				
L	0.00	0.03			
L2	0.40 RFF				

MOUNTING FOOTPRINT* SOLDERMASK DEFINED

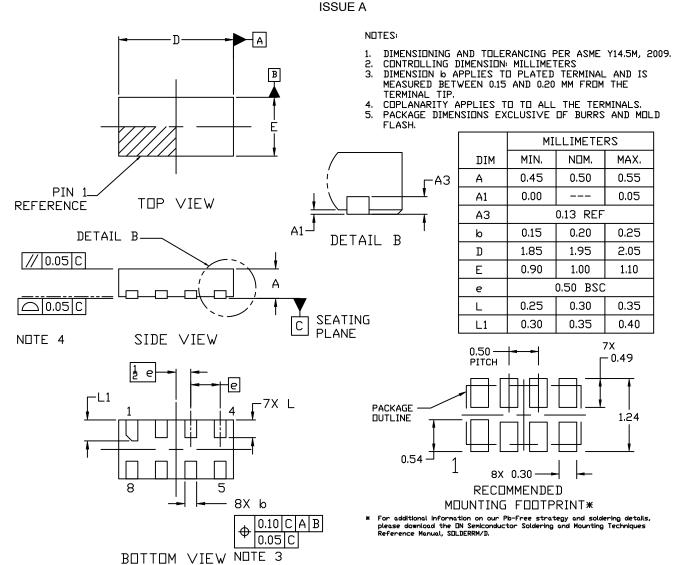


DIMENSIONS: MILLIMETERS

^{*}For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

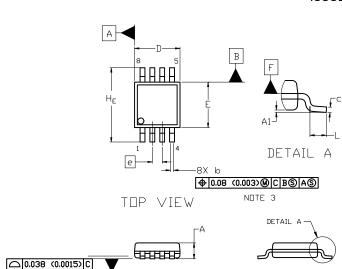
UDFN8 1.95x1.0, 0.5P CASE 517CA



PACKAGE DIMENSIONS

Micro8 CASE 846A ISSUE K

END VIEW



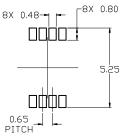
SIDE VIEW

С

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION 6 DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.10 mm IN EXCESS OF MAXIMUM MATERIAL CONDITION.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 mm PER SIDE. DIMENSION E DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 mm PER SIDE. DIMENSIONS D AND E ARE DETERMINED AT DATUM F.
- 5. DATUMS A AND B ARE TO BE DETERMINED AT DATUM F.
- 6. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

DIM



MIN. NDM. MAX. 1.10 Α A1 0.05 0.08 0.15 b 0.25 0.33 0.40 0.23 c 0.13 0.18 D 2.90 3.00 3.10 Ε 2.90 3.00 3.10 0.65 BSC e HE 4.75 4.90 5.05 0.40 0.55 0.70

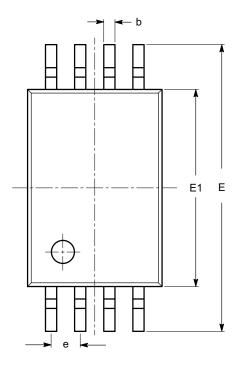
MILLIMETERS

RECOMMENDED MOUNTING FOOTPRINT

soldering details, please download the DN Seniconductor Soldering and Mounting Techniques Reference Manual, SDLDERRY/D.

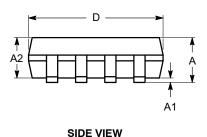
PACKAGE DIMENSIONS

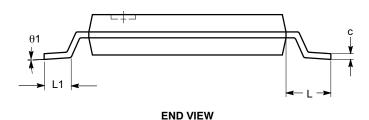
TSSOP8, 4.4x3 CASE 948AL ISSUE O



SYMBOL	MIN	NOM	MAX		
Α			1.20		
A1	0.05		0.15		
A2	0.80	0.90	1.05		
b	0.19		0.30		
С	0.09		0.20		
D	2.90	3.00	3.10		
E	6.30	6.40	6.50		
E1	4.30	4.40	4.50		
е	0.65 BSC				
L	1.00 REF				
L1	0.50	0.60	0.75		
θ	0°		8°		







Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MO-153.

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PI3B3245QEX PI3B3245QE PI3CH1000LE PI3CH400ZBEX PI3CH401LE PI3CH401LEX TC7WBL3305CFK(5L,F
74CB3Q3125DBQRE4 TC7WBL3305CFK,LF SN74CBT16245CDGGR 72V90823PQFG PI3B3861QEX PI3C3126QEX PI3C3245QE
PI5C3384QE PI3CH281QE QS3VH16244PAG8 PI3C3306LE PI3C3305LE PI5C3245LE PI3CH400LE PI3B3245LEX PI3B3245LE
PI3C3306LEX PI5C3245LEX PI5C3306LEX PI3B3126LE 74CBTLV3384PGG 74CBTLV3862PGG QS3125QG8 QS3126QG
QS32245QG QS32X384Q1G